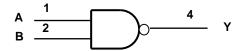


Pin Descriptions

Pin Name	Description				
Α	Data Input				
В	Data Input				
GND	Ground				
Y	Data Output				
Vcc	Supply Voltage				

Logic Diagram



Function Table

Inp	Output	
Α	В	Υ
Н	Н	L
L	Х	Н
Χ	L	Н



Absolute Maximum Ratings (Note 3)

Symbol	Description	Rating	Unit
ESD HBM	Human Body Model ESD Protection	2	KV
ESD MM	Machine Model ESD Protection	200	V
V _{CC}	Supply Voltage Range	-0.5 to 6.5	V
V _I	Input Voltage Range	-0.5 to 6.5	V
V _o	Voltage applied to output in high impedance or I _{OFF} state	-0.5 to 6.5	V
V _o	Voltage applied to output in high or low state	-0.3 to V _{CC} +0.5	V
I _{IK}	Input Clamp Current V _I <0	-50	mA
I _{OK}	Output Clamp Current	-50	mA
Io	Continuous output current	±50	mA
	Continuous current through Vdd or GND	±100	mA
T _J	Operating Junction Temperature	-40 to 150	°C
T _{STG}	Storage Temperature	-65 to 150	°C

Note: 3. Stresses beyond the absolute maximum may result in immediate failure or reduced reliability. These are stress values and device operation should be within recommend values.



Recommended Operating Conditions (Note 4)

Symbol		Parameter	Min	Max	Unit
\/	On anating Valtage	Operating	1.4	5.5	V
V_{CC}	Operating Voltage	Data retention only	1.2		V
		V _{CC} = 1.4 V to 1.95 V	0.65 X V _{CC}		
W	High lovel langet Voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	1.7		V
V_{IH}	V _{IH} High-level Input Voltage	V _{CC} = 3 V to 3.6 V	2		V
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$	0.7 X V _{CC}		
·		V _{CC} = 1.4 V to 1.95 V		0.35 X V _{CC}	
W	Lave lavel langet valta as	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		0.7	V
V_{IL}	Low-level input voltage	V _{CC} = 3 V to 3.6 V		0.8	V
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$		0.3 X V _{CC}	
VI	Input Voltage		0	5.5	V
Vo	Output Voltage		0	V _{CC}	V
		Vcc=1.4 V		-3	
		V _{CC} = 1.65 V		-4	
	I light loved autout accordant	V _{CC} = 2.3 V		-8	mA
I _{OH}	High-level output current	V 2.V		-16	IIIA
		$V_{CC} = 3 V$		-24	
		V _{CC} = 4.5 V		-32	
		Vcc=1.4 V		3	
		V _{CC} = 1.65 V		4	
ı	l avv laval avtavt avment	V _{CC} = 2.3 V		8	mΑ
I _{OL}	Low-level output current			16	
		$V_{CC} = 3 V$		24	
		V _{CC} = 4.5 V		32	
		V _{CC} = 1.4 to 3V		20	
$\Delta t/\Delta V$	Input transition rise or fall	$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$		10	ns/V
	rate	$V_{CC} = 5 \text{ V} \pm 0.5 \text{ V}$		5	
T _A	Operating free-air temperature		-40	85	°C

Note: 4. Unused inputs should be held at Vcc or Ground.



Electrical Characteristics (All typical values are at Vcc = 3.3V, T_A = 25°C)

Over recommended free-air temperature range (unless otherwise noted)

Symbol	Parameter	Test Conditions	Vcc	Min	Тур.	Max	Unit	
		I _{OH} = -100μA	1.4 V to 5.5V	V _{CC} - 0.1				
		$I_{OH} = -3mA$	1.4 V	1.05				
		$I_{OH} = -4mA$	1.65 V	1.2				
V_{OH}	High Level Output Voltage	$I_{OH} = -8mA$	2.3V	1.9			V	
	Voltage	I _{OH} = -16mA	3 V	2.4				
		$I_{OH} = -24mA$	3 V	2.3				
		$I_{OH} = -32mA$	4.5 V	3.8				
		$I_{OL} = 100 \mu A$	1.4 V to 5.5V			0.1		
		$I_{OL} = 3mA$	1.4 V			.4		
		I _{OL} = 4mA	1.65 V			0.45		
V_{OL}	V _{OL} High-level Input Voltage	$I_{OL} = 8mA$	2.3V			0.3	V	
		I _{OL} = 16mA	2.1/			0.4		
		I _{OL} = 24mA	3 V			0.55		
		$I_{OL} = 32mA$	4.5			0.55		
l _l	Input Current	$V_1 = 5.5 \text{ V or GND}$	0 to 5.5 V			± 5	μΑ	
I _{OFF}	Power Down Leakage Current	$V_1 \text{ or } V_0 = 5.5V$	0			± 10	μA	
I _{cc}	Supply Current	$V_I = 5.5V$ of GND $I_O=0$	1.4 V to 5.5V			10	μA	
Δl _{cc}	Additional Supply Current	One input at V _{CC} – 0.6 V Other inputs at V _{CC} or GND	3 V to 5.5V			500	μΑ	
Ci	Input Capacitance	$V_i = V_{CC} - \text{ or GND}$	3.3		3.5		pF	
	T	SOT25	(Note 5)		204			
θ_{JA}	Thermal Resistance Junction-to-Ambient	SOT353	(Note 5)		371		°C/W	
	Julionoli-to-Ambient	DFN1410	(Note 5)		430			
		SOT25	(Note 5)		52			
θ_{JC}	Thermal Resistance Junction-to-Case	SOT353	(Note 5)		143		°C/W	
	Juniciion-10-0458	DFN1410	(Note 5)		190			

Note: 5. Test condition for SOT25, SOT353, and DFN1410: Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.



Switching Characteristics

Over recommended free-air temperature range, CL = 15pF (see Figure 1)

Parameter	From	то	Vcc = ± 0			: 1.8 V .15V		: 2.5 V).2V		3.3 V 3.3V	Vcc :	= 5 V).5V	Unit
	(Input)	(OUTPUT)	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
t _{pd}	A or B	Υ	2.2	7.2	1.5	5	0.6	3.5	0.6	3.1	0.7	3	ns

Over recommended free-air temperature range, CL = 30 or 50pF as noted (see Figure 2)

Parameter	From	то	Vcc = ± 0			: 1.8 V .15V		: 2.5 V).2V		3.3 V 3.3 V	Vcc :	= 5 V).5V	Unit
	(Input)	(OUTPUT)	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
t _{pd}	A or B	Υ	3.1	9	2.1	6.3	1	4.4	0.8	3.8	0.9	3.6	ns

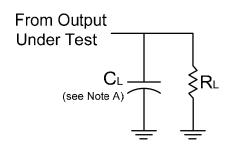
Operating Characteristics

 $T_A = 25$ °C

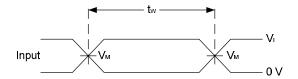
P	arameter		Vcc = 1.5 V	Vcc = 1.8 V	Vcc = 2.5 V	Vcc = 3.3 V	Vcc = 5 V	Unit
		Conditions	TYP	TYP	TYP	TYP	TYP	
C _{pd}	Power dissipation capacitance	f = 10 MHz	22	22	22	23	25	pF



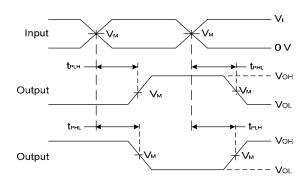
Parameter Measurement Information



Vcc	In	puts	V	6	В
VCC	Vı	t _r /t _f	V _M	CL	R _L
1.5V±0.10V	V _{CC}	≤2ns	V _{CC} /2	15pF	1ΜΩ
1.8V±0.15V	V _{CC}	≤2ns	V _{CC} /2	15pF	1ΜΩ
2.5V±0.2V	V _{cc}	≤2ns	V _{CC} /2	15pF	1ΜΩ
3.3V±0.3V	3V	≤2.5ns	1.5V	15pF	1ΜΩ
5V±0.5V	V _{cc}	≤2.5ns	V _{CC} /2	15pF	1ΜΩ



Voltage Waveform Pulse Duration



Voltage Waveform
Propagation Delay Times
Inverting and Non Inverting Outputs

Notes: A. Includes test lead and test apparatus capacitance.

B. All pulses are supplied at pulse repetition rate ≤ 10 MHz.

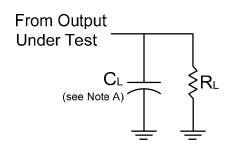
C. Inputs are measured separately one transition per measurement.

D. t_{PLH} and t_{PHL} are the same as $t_{PD.}$

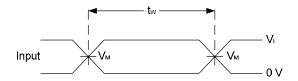
Figure 1. Load Circuit and Voltage Waveforms



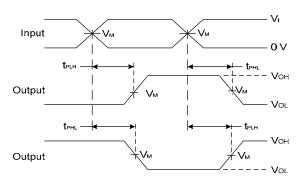
Parameter Measurement Information (Continued)



Vcc	Inp	outs	V _M	CL	R_L
	Vı	t _r /t _f	- IVI	OL.	
1.5V±0.10V	V _{CC}	≤2ns	V _{CC} /2	30pF	1ΚΩ
1.8V±0.15V	V _{CC}	≤2ns	V _{CC} /2	30pF	1ΚΩ
2.5V±0.2V	V _{CC}	≤2ns	V _{CC} /2	30pF	500Ω
3.3V±0.3V	3V	≤2.5ns	1.5V	50pF	500Ω
5V±0.5V	V _{CC}	≤2.5ns	V _{CC} /2	50pF	500Ω



Voltage Waveform Pulse Duration



Voltage Waveform
Propagation Delay Times
Inverting and Non Inverting Outputs

Notes: A. Includes test lead and test apparatus capacitance.

B. All pulses are supplied at pulse repetition rate ≤ 10 MHz.

C. Inputs are measured separately one transition per measurement.

D. t_{PLH} and t_{PHL} are the same as $t_{PD.}$

Figure 2. Load Circuit and Voltage Waveforms



Ordering Information

T4LVCE1G 00 XXX - 7

Logic Device Function Package Packing

74: Logic Prefix 00: 2-Input W5: SOT25 7: Tape & Reel

SE: SOT353 FZ4: DFN1410

LVCE: 1.4 to 5.5V NAND-Gate Family

1G : One gate

Packaging 7" Tape and Reel **Package Device** Part Number Suffix Quantity Code (Note 5) % 74LVCE1G00W5-7 W6 SOT25 3000/Tape & Reel -7 % 74LVCE1G00SE-7 SE **SOT353** 3000/Tape & Reel -7 ₱ 74LVCE1G00FZ4-7 FZ4 DFN1410 5000/Tape & Reel -7

Note: 6. Pad layout as shown on Diodes Inc. suggested pad layout document AP02001, which can be found on our website at http://www.diodes.com/datasheets/ap02001.pdf.



Marking Information

(1) SOT25 and SOT353

(Top View)

5

2

1

XX: Identification code Y: Year 0~9

XX Y W X

 \underline{W} : Week : A $^{\sim}$ Z : 1 $^{\sim}$ 26 week; a~z: 27~52 week; z represents 52 and 53 week

X: A~Z: Internal code 3

Part Number	Package	Identification Code
74LVCE1G00W5	SOT25	PS
74LVCE1G00SE	SOT353	PS

(3) DFN1410

(Top View)

XX $\underline{Y}\underline{W}\underline{X}$ XX: Identification Code

Y: Year: 0~9

 \overline{W} : Week: A~Z: 1~26 week;

a~z: 27~52 week; z represents

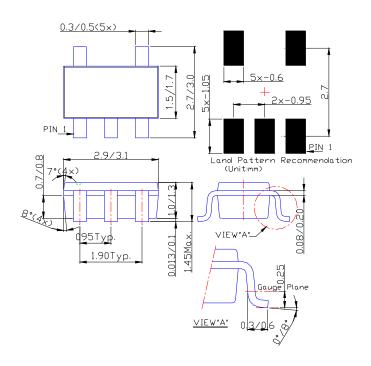
52 and 53 week X: A~Z: Internal code

Part Number	Package	Identification Code
74LVCE1G00FZ4	DFN1410	PS

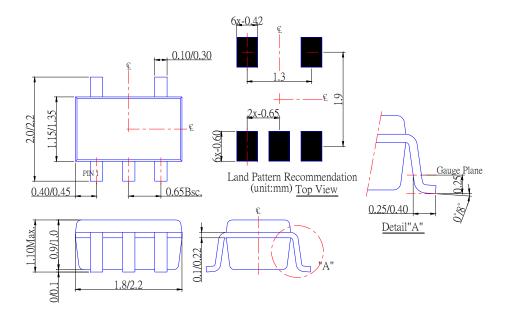


Package Outline Dimensions (All Dimensions in mm)

(1) Package Type: SOT25



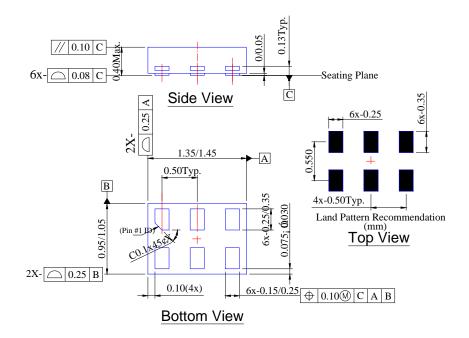
(2) Package Type: SOT353





Package Outline Dimensions (Continued)

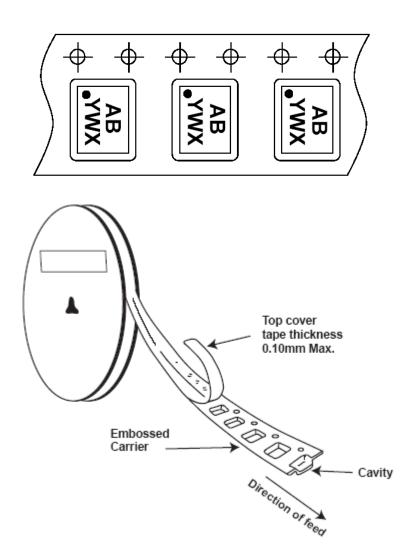
(3) Package Type: DFN1410





Taping Orientation (Note 7)

For DFN1410



Note: 7. The taping orientation of the other package type can be found on our website at http://www.diodes.com/datasheets/ap02007.pdf



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